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FORM PTO-1595 1-31-92 07-01-1999



08-842271

U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office Docket No. SEC.118

101053160

o the Honorable Commissioner of Patents and Trademarks. Pleas	se record the attached original documents or copy thereof.
Name of conveying party(ies):	Name and address of receiving party(ies):
KIM, Dong-won	
Additional names of conveying party(ies) attached?  U yes S no	Name: Samsung Electronics Co., Ltd. Internal Address:
3. Nature of Conveyance	Street Address: 416, Maetan-dong, Paldal-gu, Suwon-city City Kyungki-do
Assignment	State Republic of Korea Zip Zip Additional name(s) & address(es) attached? ☐ yes ☐ no
Execution Date: March 24, 1997	
4. Application number(s) or patent number(s):	
Title: METHOD OF ANALYZING A WAFER I FABRICATION PROCESS	IN A SEMICONDUCTOR DEVICE
If this document is being filed together with a new application, the	execution date of the application isApril 24, 1997
A. Patent Application No(s).	B. Patent No(s).
Additional numbers attac	hed? □ Yes On No
<ol><li>Name and address of party to whom correspondence concerning document should be mailed:</li></ol>	6. Total number of applications and patents involved:1_
Raymond C. Jones, Esq. Jones & Volentine, L.LP. 11921 Freedom Drive, Suite 550 Reston, Virginia 22090	7. Total fee (37 CFR 3.41): \$_40.00  © Enclosed  Authorized to be charged to deposit account  Total fee due  Any deficiencies in the enclosed fees
CERTIFICATE OF MAILING UNDER 37 CFR 1.10  I hereby certify that, on the date shown below, this correspondence is being deposited with the United States Postal Service in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231, as "Express Mail Post Office to Addressee"  Mailing Label No.  on	8. Deposit account number:  < >
9. Statement and signature  To the best of my knowledge and belief, the foregoing information is document.  Raymond C. Jones Name of Person Signing Registration #34,631  Tel.: (703) 847-3617	rue and correct and any attached copy is a true copy of the original  4/24/87  Date  Total number of pages including cover sheet: _2

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## ASSIGNMENT

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WHEREAS, I/We

Dong-won KIM	of 172-1, Namgajwa 2-dong, Sodamun-gu, Seoul, Republic of Korea

(hereinafter called ASSIGNOR) have invented certain new and useful improvements for a METHOD OF ANALYZING A WAFER IN A SEMICONDUCTOR DEVICE FABRICATION PROCESS for which an application for Letters Patent of the United States is filed herewith, claiming priority to Korean Patent Application No. 96-26767, filed July 2, 1996;

AND WHERE AS, SAMSUNG ELECTRONICS CO, LTD., of the Republic of Korea, a Korean corporation having a place of business at 416, Maetan-dong, Paldal-gu, Suwon-city, Kyungki-do, Republic of Korea (hereinafter called ASSIGNEE), desires to acquire the entire right, title and interest in and to said invention, said application and in, to and under any and all United States and foreign patents to be obtained therefore;

Now Therefore, for good and valuable consideration paid to me/us by the said ASSIGNEE, receipt of which is hereby acknowledged, I/we do hereby sell, assign and transfer to ASSIGNEE, its successors and assigns, the entire right, title and interest in and to the application and the invention disclosed therein for the United States and foreign countries, and all rights of priority resulting from the filing of said United States application, and I/we request the Commissioner of Patents to issue any Letters Patent granted upon the invention set forth in said application to ASSIGNEE, its successors and assigns; and I/we hereby agree that ASSIGNEE may apply for foreign patents on said invention and I/we will execute all papers necessary in connection with the United States and foreign applications when called upon to do so by ASSIGNEE.

Dong-won KIM

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on Date <u>03/24</u>, 19<u>97</u>

RECORDED: 04/24/1997

PATENT REEL: 9913 FRAME: 0248